

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

- 1-5. (Cancelled)
6. (Currently amended) A recycling method for recycling waste particles comprising:  
machining a crystal ingot into a wafer or machining a semiconductor wafer;  
solidifying into a cake, particles generated by machining the crystal ingot or the  
semiconductor wafer;  
transporting the cake where dryness is prevented; and  
melting the cake.
7. (Currently amended) A recycling method for recycling waste particles comprising:  
machining a crystal ingot into a wafer or machining a semiconductor wafer;  
solidifying into a cake, particles generated by machining the crystal ingot or the  
semiconductor wafer;  
transporting the cake where dryness is prevented; and  
recycling said cake as an ingot.
8. (Currently amended) A recycling method for recycling waste particles comprising:  
machining a crystal ingot into a wafer or machining a semiconductor wafer;  
solidifying into a cake at a predetermined water content, particles generated by  
machining the crystal ingot or the semiconductor wafer;  
transporting the cake where dryness is prevented; and  
melting said cake to recycle said cake as an ingot.

9. (Currently amended) A method for fabricating a semiconductor ingot comprising:  
machining a crystal ingot into a wafer or machining a semiconductor wafer;  
solidifying into a cake at a predetermined water content and without any chemical  
reactions, particles generated by machining the crystal ingot or the semiconductor wafer;  
transporting the cake where dryness is prevented; and  
melting said cake.

10. (Previously presented) A recycling method according to one of claims 6 to 8,  
wherein machining comprises abrading, grinding or polishing, dicing, back grinding or wafer  
polishing.

11. (Previously presented) A method according to claim 9, wherein machining comprises  
abrading, grinding or polishing, dicing, back grinding or wafer polishing.

12- 18. (Cancelled)

19. (Currently amended) A method for processing particles comprising:  
solidifying into a cake, particles that are generated by machining a crystal ingot into a  
wafer or machining a semiconductor wafer;  
transporting the cake where dryness is prevented; and  
melting the cake into an ingot.

20. (Previously presented) A method according to claim 19, further comprising:  
solidifying said particles at a predetermined water content, without any chemical  
reactions.

21. (Previously presented) A method according to claim 19, wherein machining comprises abrading, grinding or polishing.

22. (Previously presented) A method according to claim 19, wherein machining said semiconductor wafer comprises dicing, back grinding or wafer polishing.

23. (Previously presented) A method according to claim 19, wherein said particles comprises Si flakes.

24. (Currently amended) A recycling method for recycling waste particles, comprising:  
transporting a cake where dryness is prevented; and  
melting the [a] cake which is produced by solidifying particles generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.

25. (Currently amended) A recycling method for recycling waste particles comprising:  
transporting a cake where dryness is prevented; and  
melting the [a] cake to recycle the cake as an ingot, said cake produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content.

26. (Currently amended) A method for fabricating a semiconductor ingot comprising:  
transporting a cake where dryness is prevented; and  
melting the [a] cake which is produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content and without any chemical reactions.

27. (Currently amended) A method for processing particles comprising:  
transporting a cake where dryness is prevented; and

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melting the [a] cake into an ingot, said cake produced by solidifying particles that are generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.